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ABSTRACT

A resin sealing type semiconductor device comprises an element mounting member (10) having an element mounting surface (12), a semiconductor element (20) bonded to the element mounting surface (12), a plurality of leads (30) provided and separated from the semiconductor element (20), a frame lead (36) disposed between these leads (30) and the semiconductor element (20), various wires (40) and a resin sealing portion which seals the element mounting member (10), the semiconductor element (20), parts of the leads (30) and the frame lead (36). The leads (30) include first inner leads (32a) disposed discontinuously with the frame lead (36) and second leads (32b) disposed integrally with the frame lead (36).

The resin sealing type semiconductor device has good heat radiation characteristics and high reliability. Wire bonding with a highly flexible wiring arrangement design is provided by using leads commonly.